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Semiconductor devices - Mechanical and climatic test methods -  
Part 23: High temperature operating life

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**Semiconductor devices - Mechanical and climatic test methods -  
Part 23: High temperature operating life**

FOREWORD

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IEC 60749-23 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition cancels and replaces the first edition published in 2004 and Amendment 1:2011. It is based on JEDEC JESD22-A108G. It is used with permission of the copyright holder, JEDEC Solid State Technology Association. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) absolute stress test definitions and resultant test durations have been updated.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2962/FDIS	47/2983/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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